



Semiconductor Device Type: H5X QSOP-16-3.90mm-MatteTin			Package Homogeneous Materials							
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	37.65	(mg) Total	Die	% of Total Weight	31.16
Silicon	7440-21-3	Die	31.16	37.65	311608		Silicon	7440-21-3	100.00	
Copper	7440-50-8	Leadframe	26.62	32.16	266181		Total 100.00			
Iron	7439-89-6	Leadframe	0.65	0.78	6460					
Phosphorus	7723-14-0	Leadframe	0.00	0.00	41	33.21	(mg) Total	Leadframe	% of Total Weight	27.49
Zinc	7440-66-6	Leadframe	0.04	0.05	412		Copper	7440-50-8	96.835	
Silver	7440-22-4	Leadframe	0.18	0.22	1787		Iron	7439-89-6	2.35	
Silver	7440-22-4	Die Attach Material	0.51	0.62	5102		Phosphorus	7723-14-0	0.015	
exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	Die Attach Material	0.09	0.11	931		Zinc	7440-66-6	0.15	
1,1'-(1,3-phenylene)bis-1H-pyrrole-2,5-dione	3006-93-7	Die Attach Material	0.01	0.01	109		Silver	7440-22-4	0.65	
Epoxy Resin	Trade Secret	Die Attach Material	0.00	0.00	31		Total 100.00			
2-(3,4-Epoxy)cyclohexyl)ethyltrimethoxysilane	3388-04-3	Die Attach Material	0.00	0.00	31					
2-Methylhydroquinone	95-71-6	Die Attach Material	0.00	0.00	3	0.75	(mg) Total	Die Attach Material	% of Total Weight	0.62
Gold	7440-57-5	Bonding Wire	0.34	0.41	3414		Silver	7440-22-4	82.20	
Epoxy resin A	Trade Secret	Molding Compound (Encapsulation)	1.43	1.73	14293		exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	15.00	
Epoxy resin B	29690-82-2	Molding Compound (Encapsulation)	0.71	0.86	7147		1,1'-(1,3-phenylene)bis-1H-pyrrole-2,5-dione	3006-93-7	1.75	
Phenol Resin	Trade Secret	Molding Compound (Encapsulation)	1.39	1.68	13936		Epoxy Resin	Trade Secret	0.50	
Silica (Amorphous)	60676-86-0	Molding Compound (Encapsulation)	32.16	38.86	321601		2-(3,4-Epoxy)cyclohexyl)ethyltrimethoxysilane	3388-04-3	0.50	
Carbon Black	1333-86-4	Molding Compound (Encapsulation)	0.04	0.04	357		2-Methylhydroquinone	95-71-6	0.05	
Tin	7440-31-5	Lead Finish Plating	4.66	5.63	46555		Total 100.00			
TOTALS: 100.00 120.83 1,000,000										
120.83 mg Total Mass										
						0.41	(mg) Total	Bonding Wire	% of Total Weight	0.34
							Gold	7440-57-5	100.00	
						Total 100.00				
						43.18	(mg) Total	Molding Compound (Encapsulation)	% of Total Weight	35.73
							Epoxy resin A	Trade Secret	4.00	
							Epoxy resin B	29690-82-2	2.00	
							Phenol Resin	Trade Secret	3.90	
							Silica (Amorphous)	60676-86-0	90.00	
							Carbon Black	1333-86-4	0.10	
						Total 100.00				
						5.63	(mg) Total	Lead Finish Plating	% of Total Weight	4.66
							Tin	7440-31-5	100.00	
						120.83	Total		100.00	100.00

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